

# **PSE Technology Corporation**

## SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	32.768 KHz
HOLDER TYPE	TYPE G3 Cylinder SMD Quartz Crystal
SPEC. NO. ( P/N )	G33270007
CUSTOMER P/N	-
ISSUE DATE	Apr.25,2011
VERSION	D

APPROVED	PREPARED	QA
Brenda	Clane	Canthur
APPROVED BY CUSTOMER:		AVL Status
Please return one copy	with approval to PSE-TW	

### **PSE Technology Corporation**

No.2, Tzu-Chiang 5th Rd, Chung Li Industrial Park, Chung Li City, Taoyuan County, Taiwan (R.O.C.)

TEL: 886-3-451-8888 FAX: 886-3-461-3865

http://www.saronix-ecera.com.tw

- \*RoHS Exception
- \*HF-Halogen Free
- \*REACH Compliant



\*\*\* A company of PERICOM Semiconductor Corporation \*\*\*

G33270007

VER. D 25-Apr-11

### **VERSION HISTORY**

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
А	Mar.12,2010			Initial Release	
В	Jul.23,2010			Changed Pb- Free to RoHS Compliant by Exemption	
С	Aug.26,2010			Correct Marking from 32.768 to 32768	
D	Apr.25,2011			Revised format	



G33270007

VER. D 25-Apr-11

#### **ELECTRICAL SPECIFICATIONS**

SRe Part Number: G33270007

Parameters	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	32.768	KHz	
Mode of Oscillation	МО	Fundamental		+2° X-Cut
Load Capacitance	CL	12.5	pF	Typical
Calibration Tolerance		± 20	ppm	at 25℃ ± 5℃
Operating Temperature Range	TR	-40~85	°C	
Drive Level	DL	1	$\mu$ W	Max.
Series Resonant Resistance	CI/RR	50	ΚΩ	Max.
Temperature Coefficient	K	-0.035	ppm/°C <sup>2</sup>	Typical
Aging		± 3	ppm	Max 1st year
Insulation Resistance		500	ΜΩ	at DC 100V ± 15V

#### Reliability ( Mechanical and Environmental Endurance )

No.	Test Items	Test Method and Condition	Requirements
1	Vibration	(1) Vibration Frequency: 10 to 55Hz	Frequency Change: ±10ppm Max.
		(2) Vibration Amplitude: 1.5mm	Resistance Change: ±15% or 5kΩ Max.
		(3) Cycle Time: 1-2min(10-55-10Hz)	
		(4) Direction: X.Y.Z	
		(5) Duration: 2h/each direction	
2	Shock	3 Times free drop from 75cm height to hard wooden	Frequency Change: ±10ppm Max.
		board of thickness more than 30mm	Resistance Change: ±15% or 5kΩ Max.
3	Hermetic seal	Checked:before the molded crystal uints	less than 1 × 10 EXP(-7) mbar.l/sec.
4	High temperature	240 hours at +85°ℂ±2°ℂ	Frequency Change:±10ppm Max.
		After 1-2hours past at room temperature from following	Resistance Change:±25% or 10kohm Max.
		test.	



G33270007 VER. D 25-Apr-11

	After 1-2hours past at room temperature from following	Danistana Ohamas (450/ an Eliabas Mass
	rator i znoura pust at room temperature mom following	Resistance Change:±15% or 5konm Max.
	test.	
Humidity	240 hours at +85°C±2°C, relative humidity 90-95%	Frequency Change:±10ppm Max.
	After 1-2hours past at room temperature from following	Resistance Change:±25% or 10kohm Max.
	test.	
Temperature cycle	After supplying the following temperature cycle	Frequency Change:±10ppm Max.
	(50cycles)	Resistance Change:±25% or 10kohm Max.
	+100deg.C 30min 1 to 2min 30min 1 to 2min 1 to 2min 1 to 2min 30min	
Solderability	Dip the leads of crystal units into the solution (7-10%)	The dipped surface of the leads should be
	of rosin 3±0.5s,then dip it into the tank 5-10s.	at least 95% covered withcontinuous new
	Temperature of solder melted tank is 245°C±5°C	solder coating
Reflow soldering	The REFLOW SOLDERING PROFILE of Fig.1 for	After 24h past from frequency test,
	TMXLi-206F families.	Frequency Change:±10ppm Max.
	REFLOW SOLDERING PROFILE	Resistance Change:±25% or 10kohm Max.
		Notice:
	260°C peak.	1、Using the infrared lamp at soldering
	250 250°C 250°C	process may cause uneven temperature
	200 170±10°C	rise on plastic surface of the parts,so that
	150 - 120+20san	please keep the package temperature
	Note: the temperature is	within left conditions.
	the PCB surface temperature.  50 100 150 200 250	2 \ DO NOT dip the plastic part into
	Time(sec.)	solder.
	Solderability	test.  Temperature cycle  After supplying the following temperature cycle  (50cycles)  #100deg.C  40deg.C  1 to 2min  1 t



Page 2 E0-R-4-014 Rev.E

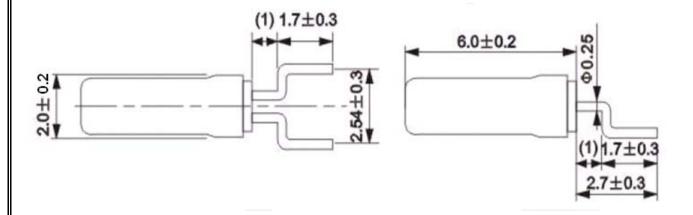
G33270007

VER. D 25-Apr-11

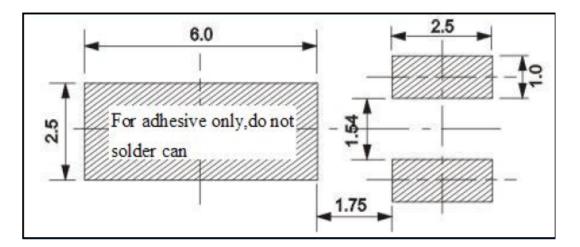
**MARKING** 

32768

**DIMENSIONS** (Unit:mm)



### SOLDER PATTERN



#### **TYPE G3 Cylinder SMD Quartz Crystal** G33270007 VER. D 25-Apr-11 **Packing** Ш 0.3 ≥ 8 ΚQ 0.7±0.1 Α0 2.1 P0 D0ΚO BO Α0 W 2.3 +0.10 4.0+0.10 2 +0.15 9.7 +0.10 1.75 +0.10 7.5 -0.10 1.5+0.15 +0,30 +0.10 +0.10 +0.10 16 \_0.30 -0.10 -0.10 -0.10 -0.10 -0.10 -0.00 W2 (6) W1 W2+0.4 D±0.3 W1±0.2 A±0.5 C±0.2 330 25 100 20 16



G33270007

VER. D 25-Apr-11

### **Packing**

